19-4598; Rev 1; 7/09

EVALUATION KIT AVAILABLE

MAXM

16-Bit, RISC, Microcontroller-Based, Ultrasonic Distance-Measuring System

Delta ADC)

Sampling Rate

General Description

Features

The MAXQ7667 smart system-on-a-chip (SoC) provides a time-of-flight ultrasonic distance-measuring solution. The device is optimized for applications involving large distance measurement with weak input signals or multiple target identification. The MAXQ7667 features high signalto-noise ratio achieved by combining flexible electronics with the intelligence necessary to optimize each function as environmental and target conditions change. ♦ **Smart Analog Peripherals**

An integrated burst signal generator and echo reception components process ultrasonic signals between 25kHz and 100kHz. Echo reception components include a programmable gain low-noise amplifier (LNA), a 16-bit sigma-delta ADC to digitize the received echo signals, and digital signal processing (DSP). DSP limits noise with a bandpass filter, and creates an echo envelope through demodulation and lowpass filtering. Input referred noise is a low 0.7µVRMS. A programmable phase-locked loop (PLL) frequency synthesizer supplies the reference frequency for the burst generator and the clock for the echo receiver's digital filter. An embedded 16-bit MAXQ20 microcontroller (µC) controls all the preceding functions.

The μ C optimizes the burst frequency and reception frequency for each transmission at any temperature. The MAXQ7667 achieves smart sensing by monitoring the echo signals and then actively changing the transmitted and received parameters to obtain optimum results. Digital filtering and burst synthesis do not require CPU intervention. This leaves all the CPU power available for echo optimization, communication, diagnostics, and additional signal processing.

The MAXQ7667 operates with three different power supply voltages: +5V, +3.3V, and +2.5V. Two internal linear regulators allow operation from a single +5V supply when three external power supplies are not available. Alternatively, the MAXQ7667 can control an external pass transistor to allow operation from a single supply voltage of +8V to +65V or more, depending on the external component tolerance. The device is available in a 48-pin LQFP package and is specified to operate from -40°C to +125°C.

Applications

Automotive Parking Vehicle Security

Automation Handheld Devices

Industrial Processing

♦ **High-Performance, Low-Power, 16-Bit RISC Core** ♦ **Program and Data Memory** ♦ **Crystal/Clock Module**

♦ **Timer/Digital I/O Peripherals**

♦ **16 x 16 Hardware Multiplier with 48-Bit Accumulator, Single Clock Cycle**

Dedicated Ultrasonic Burst Generator

Echo Receiving Path (Includes LNA, Sigma-

5-Channel, 12-Bit SAR ADC with 250ksps

Internal Bandgap Voltage Reference for the

- ♦ **Power-Management Module**
- ♦ **JTAG Interface**
- ♦ **Universal Asynchronous Receiver-Transmitter (UART)**
- ♦ **Local Interconnect Network (LIN)**

See the Detailed Features section for complete list of features.

Ordering Information

Note: All devices are specified over the -40°C to +125°C operating temperature range.

/V denotes an automotive qualified part.

+Denotes a lead(Pb)-free/RoHS-compliant package.

Pin Configuration appears at end of data sheet.

MAXQ7667 MAXQ7667 ADCs (Also Accepts External Voltage Reference)

Note: Some revisions of this device may incorporate deviations from published specifications known as errata. Multiple revisions of any device may be simultaneously available through various sales channels. For information about device errata, go to: **ww.maxim-ic.com/errata**.

MAXM

__ Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

DVDDIO, GATE5, REG3P3, REG2P5 to

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(VDVDDIO = +5V, VAVDD = +3.3V; VDVDD = +2.5V, system clock (fsyscLK) = 16MHz, burst frequency (f $BURST$) = bandpass frequency (fBPF) = 50kHz, CREFBG = CREF = 1µF in parallel with 0.01µF, fADCCLK = 2MHz (SAR data rate = 125ksps), TA = TMIN to TMAX, unless otherwise specified. Typical values are at $T_A = +25^{\circ}C$.)

ELECTRICAL CHARACTERISTICS (continued)

(V_{DVDDIO} = +5V, V_{AVDD} = +3.3V; V_{DVDD} = +2.5V, system clock (f_{SYSCLK}) = 16MHz, burst frequency (f_{BURST}) = bandpass frequency (fBPF) = 50kHz, CREFBG = CREF = 1µF in parallel with 0.01µF, fADCCLK = 2MHz (SAR data rate = 125ksps), TA = TMIN to TMAX, unless otherwise specified. Typical values are at T_A = +25°C.)

ELECTRICAL CHARACTERISTICS (continued)

(V_{DVDDIO} = +5V, V_{AVDD} = +3.3V; V_{DVDD} = +2.5V, system clock (f_{SYSCLK}) = 16MHz, burst frequency (f_{BURST}) = bandpass frequency (fBPF) = 50kHz, CREFBG = CREF = 1µF in parallel with 0.01µF, fADCCLK = 2MHz (SAR data rate = 125ksps), TA = TMIN to TMAX, unless otherwise specified. Typical values are at $T_A = +25^{\circ}C$.)

MAXM

ELECTRICAL CHARACTERISTICS (continued)

(V_{DVDDIO} = +5V, V_{AVDD} = +3.3V; V_{DVDD} = +2.5V, system clock (f_{SYSCLK}) = 16MHz, burst frequency (f_{BURST}) = bandpass frequency (fBPF) = 50kHz, CREFBG = CREF = 1µF in parallel with 0.01µF, fADCCLK = 2MHz (SAR data rate = 125ksps), TA = TMIN to TMAX, unless otherwise specified. Typical values are at $T_A = +25^{\circ}C$.)

ELECTRICAL CHARACTERISTICS (continued)

(V_{DVDDIO} = +5V, V_{AVDD} = +3.3V; V_{DVDD} = +2.5V, system clock (f_{SYSCLK}) = 16MHz, burst frequency (f_{BURST}) = bandpass frequency (fBPF) = 50kHz, CREFBG = CREF = 1µF in parallel with 0.01µF, fADCCLK = 2MHz (SAR data rate = 125ksps), TA = TMIN to TMAX, unless otherwise specified. Typical values are at $T_A = +25^{\circ}C$.)

SPI is a trademark of Motorola, Inc.

ELECTRICAL CHARACTERISTICS (continued)

(V_{DVDDIO} = +5V, V_{AVDD} = +3.3V; V_{DVDD} = +2.5V, system clock (f_{SYSCLK}) = 16MHz, burst frequency (f_{BURST}) = bandpass frequency (fBPF) = 50kHz, CREFBG = CREF = 1µF in parallel with 0.01µF, fADCCLK = 2MHz (SAR data rate = 125ksps), TA = TMIN to TMAX, unless otherwise specified. Typical values are at $T_A = +25^{\circ}C$.)

ELECTRICAL CHARACTERISTICS (continued)

(V_{DVDDIO} = +5V, V_{AVDD} = +3.3V; V_{DVDD} = +2.5V, system clock (f_{SYSCLK}) = 16MHz, burst frequency (f_{BURST}) = bandpass frequency (fBPF) = 50kHz, CREFBG = CREF = 1µF in parallel with 0.01µF, fADCCLK = 2MHz (SAR data rate = 125ksps), TA = TMIN to TMAX, unless otherwise specified. Typical values are at $T_A = +25^{\circ}C$.)

Note 1: Noise measured at bandpass filter output with ECHO+ and ECHO- shorted divided by the gain with f_{BPF} = 50kHz.

Note 2: Gain adjust resolution typically ranges between 6.25% and 12.5%.

Note 3: LIN 2.0 specifies a maximim data rate of 20kbps. Higher data rates could be possible with compatible devices and suitable line conditions.

MAXM

Typical Operating Characteristics

(VDVDDIO = +5V, VAVDD = +3.3V, VDVDD = +2.5V, fsyscl $K = 16$ MHz, burst frequency = bandpass frequency = 50kHz, TA = +25°C, unless otherwise noted.)

NAIXINI

MAXQ7667 MAXQ7667

(VDVDDIO = +5V, VAVDD = +3.3V, VDVDD = +2.5V, fs $_{\text{YSCLK}}$ = 16MHz, burst frequency = bandpass frequency = 50kHz, T_A = +25°C, unless otherwise noted.)

MAXM

MAXQ7667

MAXQ7667

Typical Operating Characteristics (continued)

 $(V_{DVDDIO} = +5V$, $V_{AVDD} = +3.3V$, $V_{DVDD} = +2.5V$, $f_{SYSCLK} = 16MHz$, burst frequency = bandpass frequency = 50kHz, $T_A = +25^{\circ}C$, unless otherwise noted.)

REG2P5 LOAD CURRENT (mA)

0 20 40 60 80 100 120

40 60

TEMPERATURE (°C)

Pin Description

MAXQ7667

MAXQ7667

Pin Description (continued)

Typical Application Circuit/Functional Diagram

Detailed Features

♦ **Smart Analog Peripherals Dedicated Ultrasonic Burst Generator Echo Receiving Path Low-Noise Amplifier Time Variable Gain Amplifier**

16-Bit Sigma-Delta ADC

Digital Bandpass Filter

Full-Wave Rectifier and Digital Lowpass Filter 8-Deep, 16-Bit Wide FIFO Simplifies Real-Time Processing

Magnitude Comparator

5-Channel, 12-Bit SAR ADC with 250ksps Sampling Rate

Internal Bandgap Voltage Reference for the ADCs (Also Accepts External Voltage Reference)

♦ **Timer/Digital I/O Peripherals**

SPI Interface

Three 16-Bit (or Six 8-Bit) Programmable Type 2 Timers/Counters

16-Bit Schedule Timer

Programmable Watchdog Timer

16 General-Purpose Digital I/Os with Multipurpose Capability

♦ **High-Performance, Low-Power, 16-Bit RISC Core 1MHz–16MHz Operation, Approaching 1MIPS per 1MHz**

Low Power (< 2.5mA/MIPS, DVDD = +2.5V)

16-Bit Instruction Word, 16-Bit Data Bus

33 Instructions (Most Require Only One Clock Cycle)

16-Level Hardware Stack

Three Independent Data Pointers with Automatic Increment/Decrement

- ♦ **Program and Data Memory Internal 32KB Program Flash Internal 4KB Data RAM Internal 8KB Utility ROM**
- ♦ **Crystal/Clock Module 1MHz–16MHz External Crystal Oscillator 13.5MHz Internal RC Oscillator External Clock Source Operation**
- ♦ **16 x 16 Hardware Multiplier with 48-Bit Accumulator, Single Clock Cycle Operation**
- ♦ **Power-Management Module Power-On Reset (POR) Power-Supply Supervisor/Brownout Detection for All Supplies On-Chip +5V, +3.3V, and +2.5V Regulators for Single Supply Operation**
- ♦ **JTAG Interface Extensive Debug and Emulation Support In-System Test Capability**
	- **Flash-Memory-Program Download**
- ♦ **UART**

Synchronous and Asynchronous Transfers Independent Baud-Rate Generator 2-Wire Interface

Transmit and Receive FIFOs

♦ **LIN**

Supports LIN 1.3, LIN 2.0, and SAE J2602

Automatic Baud-Rate Detection and LIN Frame Synchronization

Up to 64 Bytes Frame Length Automatic Calculation of Standard (LIN 1.3) and Enhanced (LIN 2.0) Checksums

- ♦ **7mm x 7mm, 48-Pin LQFP Package**
- ♦ **-40°C to +125°C Operating Temperature Range**

Detailed Description

The ultrasonic distance-measurement peripherals in the MAXQ7667 include a burst signal generator for acoustic transmission and mixed signal circuits for amplifying and digitizing echo signals ranging between 25kHz and 100kHz. The burst signal is a square wave with adjustable duty cycle and pulse count. The burst is derived either directly from the system clock or from a programmable PLL locked to the system clock. The MAXQ7667 effectively digitizes the echo signals received at the ECHOP and ECHON inputs using an LNA, sigma-delta ADC with variable analog gain amplifier, noise-limiting digital bandpass filter, digital fullwave rectifier, and a digital lowpass filter (see the Typical Application Circuit/Functional Diagram). The device detects echo signals at the burst frequency with amplitudes ranging from 10µV_{P-P} to 100mV_{P-P}. Echoes greater than 100mVp-p and less than 2Vp-p are internally clipped but do not saturate the receiver. To optimize echo reception, the clock used for processing the echo locks to the burst frequency. The MAXQ7667's burst generator can generate higher frequencies, but the maximum usable frequency for the echo receive path is 100kHz . For applications requiring transducer frequencies above 100kHz, implement an external echo receive path. The SAR ADC can then digitize the filtered echo envelope.

An integrated 16-bit RISC µC (MAXQ20) provides timing control, signal processing, and data I/O. The 16-bit Harvard architecture RISC core executes most instructions in a single clock cycle from instruction fetch to cycle completion. The MAXQ20 provides optimal performance for noise-sensitive analog applications.

The MAXQ7667 includes a 13.5MHz RC oscillator, external crystal oscillator, watchdog timer, schedule timer, three general-purpose Type 2 timers/counters, two 8-bit GPIO ports, SPI interface, JTAG interface, LIN capable UART interface, 12-bit SAR ADC with five multiplexed input channels, supply-voltage monitors, and a voltage reference for communication, diagnostics, and miscellaneous support.

Burst Controller

The MAXQ7667 provides a square-wave burst signal at the BURST output. Use the burst control to transmit an ultrasonic signal. Typical applications use the burst signal to switch an external transistor that drives a highvoltage transformer, which excites the transducer (see the Typical Application Circuit/Functional Diagram). Use software to configure the duty cycle, frequency, number of pulses, and drive current of the burst. See Section 17 of the MAXQ7667 User's Guide.

Derive the burst signal either directly from the system clock or from a programmable oscillator phase locked to the system clock (Figure 1). Using the system clock limits the burst frequency to one of 16 choices. Integer division of the system clock generates these 16 frequencies. The PLL allows a fractional division of the system clock. Any frequency within the PLL range is selectable to a resolution of 0.13% or better.

When using the internal PLL, connect external filter components (C1, R1, and C2) to FILT as shown in Figure 1. These components filter the analog voltage that controls the VCO in the PLL. The filter component values shown in the figure are suitable for the entire PLL frequency range.

Figure 1. Burst Transmission Stage

Echo Receive Path

Low-Noise Amplifier (LNA)

The LNA provides a 40V/V fixed gain to the input signal. The differential inputs of the LNA are ECHOP and ECHON. For proper biasing of the LNA, AC-couple the transducer or any external circuitry to ECHOP and ECHON. For a single-ended input signal, AC-couple the signal to ECHOP with a 0.01µF capacitor and connect ECHON to AGND through a 0.01µF capacitor placed as close as possible to the signal source. The outputs of the LNA connect to the inputs of a 16-bit sigma-delta ADC and can connect internally to the AIN0 and AIN1 inputs of the SAR ADC for external monitoring (Figure 2).

Diagnostic Signals An analog multiplexer located at the input of the LNA selects one of three possible signals for processing by the echo receive path; the normal echo signal AC-coupled to the ECHOP and ECHON inputs, 0V signal, or a 2mVP-P internally generated signal (Figure 2). The 2mVP-P square-wave signal, with frequency and duty cycle matching the burst signal, allows the echo receive chain to process a simulated echo.

Figure 2. Echo Receive Path

MAXQ7667

MAXQ7667

Sigma-Delta ADC

The MAXQ7667 features a 16-bit sigma-delta ADC with an analog gain adjustable from 38dB to 60dB (including the fixed LNA gain) with a maximum gain step of 12.5% (typical). Gain changes settle within one ADC conversion. Use software to create a virtual time variable gain amplifier. A digital bandpass and lowpass filters remove switching glitches and DC offset at the output of the ADC.

In a typical application, the software sets the gain to a low value when the burst is first sent and increases the gain as the time from when the burst was sent increases. As a result, strong echoes from nearby objects are processed without clipping while small signals from distant objects are processed with the maximum gain. The ADC samples the amplified echo signal from the LNA at 80 times the burst output frequency. The ADC provides conversion results at a data rate equal to 10 times the burst output frequency. The ADC conversion results also load to an 8-deep first-in-first-out (FIFO) at the native data rate or a separate time base without loading the CPU.

Digital Bandpass Filter

The digital bandpass filter has a center frequency that tracks the burst output frequency. The bandpass width is 14% of the center frequency. The bandpass filter provides the 16-bit output data at a data rate equal to 10 times the burst output frequency.

Full-Wave Rectifier

The full-wave rectifier detects the envelope of the digital bandwidth filter output to generate a DC output proportional to the peak-to-peak amplitude of the input signal. Full-wave rectification allows the digital lowpass filter to respond faster without excessive ripple.

Digital Lowpass Filter

The lowpass filter removes the ripple from the full-wave detector output. The output of the lowpass filter is available at a data rate equal to five times the burst output frequency. The corner frequency is 1/5 the burst frequency with approximately 40dB per decade rolloff. The 16-bit output data of the lowpass filter is stored in a FIFO register with a depth of eight samples. The MAXQ7667 allows data transfer from the lowpass filter

Figure 3. SAR ADC Block Diagram

output to the FIFO automatically each time the lowpass filter output updates, through the control of one of the timer outputs, or through software. The device includes a FIFO depth counter with programmable interrupt levels and generates an interrupt if a FIFO overflow condition occurs. The output of the digital lowpass filter connects to a digital comparator that can generate an interrupt for a specified echo signal level.

Digital Comparator and Threshold Adjust

The digital comparator output asserts when the echo amplitude at the output of the digital lowpass filter crosses a given threshold. The comparator's threshold level, hysteresis, and interrupt polarity are programmable.

SAR ADC

The MAXQ7667 incorporates a 12-bit unbuffered SAR ADC with sample-and-hold and conversion rate up to 250ksps. The ADC allows measurements of tempera-

Figure 4. Unipolar Transfer Function

ture, battery voltage, or other parameters using five single-ended or two fully differential analog inputs (AIN0–AIN4). All of the analog inputs have a range of 0 to VREF in unipolar mode and \pm VREF/2 in bipolar mode.

The SAR ADC supports three different conversion start sources: timers, ADC control input (ADCCTL), and software write. The conversion start source triggers the ADC acquisition and conversion. The system clock provides the ADC clock frequency programmable to 1/2, 1/4, 1/8, or 1/16 of the system clock. Use internal bandgap reference, external reference, or AVDD for voltage reference of the SAR ADC. Figure 3 shows a simplified block diagram of the SAR ADC.

The output of the SAR ADC is straight binary in unipolar mode and two's complement in bipolar mode. Figures 4 and 5 show the ADC transfer functions in unipolar mode and bipolar mode.

Figure 5. Bipolar Transfer Function

MAXQ7667 MAXQ7667

SAR ADC Analog Input Track-and-Hold (T/H)

Figures 6 and 7 show the equivalent input circuit of the MAXQ7667 analog input architecture. During acquisition (track), a sampling capacitor charges to the positive input voltage at AIN0–AIN4 in single-ended mode or AIN0 and AIN2 in differential mode while a second sampling capacitor connects to AGND in single-ended mode or AIN1 and AIN3 in differential mode. The ADC conversion start source and the ADC dual mode selection bits control the T/H timing.

Voltage Reference

The MAXQ7667 supports three possible voltage reference sources for ADC conversion; 2.5V internal buffered bandgap reference, external source, and AVDD. The internal 2.5V bandgap reference has high initial accuracy and temperature coefficient of typically less than 100ppm/°C. When operating in internal reference mode, either the buffered output of the internal reference or AVDD connects to the SAR ADC while the buffered output of the internal reference connects to the sigma-delta ADC. When operating in external reference mode, an external source ranging between 1V and VAVDD applied at either the REF or REFBG inputs pro-

Figure 6. Equivalent Input Circuit (Track/Acquisition Mode)

vides the reference to the SAR ADC and sigma-delta ADC. Bypass REFBG and REF to AGND with a 0.47µF capacitor for optimum performance. See Section 14 of the MAXQ7667 User's Guide.

Schedule Timer

The MAXQ7667's schedule timer provides general timekeeping and software synchronization to an external I/O. The schedule timer features include the following:

- 16-bit autoreload up-counter for the timer
- Programmable 16-bit alarm register
- Alarm interrupts
- Schedule timer incremented by a programmable system clock prescaler (1, 1/2, 1/4, 1/8, 1/16, 1/32, 1/64, 1/128)
- Schedule timer up-counter resettable through an external I/O pin, which allows synchronization of a schedule timer to an external event
- Wake-up alarm to pull the system clock from stopmode to normal operation

Figure 8 shows a simplified block diagram of the schedule timer.

Figure 7. Equivalent Input Circuit (Hold/Conversion Mode)

Type 2 Timers/Counters

The MAXQ7667 includes three 16-bit timers/counters with programmable I/O (Figure 9). Each timer is a Type 2 timer implemented in the MAXQ® family. The Type 2 timer is an autoreload 16-bit timer/counter offering the following functions:

- 8-bit/16-bit timer/counter
- Up/down autoreload
- Counter function of external pulse
- Capture
- Compare

Clock Sources

The MAXQ7667 oscillator module supplies the system clock for the µC core and all of the peripheral modules. The high-frequency oscillator operates with a 1MHz to 16MHz crystal. Use the internal RC oscillator as the system clock for applications that do not require precise timing. See Section 15 of the MAXQ7667 User's Guide.

The MAXQ7667 supports the following master clock sources:

• Internal high-frequency oscillator drives an external 1MHz–16MHz crystal or ceramic resonator

- Internal, fast-starting, 13.5MHz RC oscillator (default oscillator at startup and in the event the external crystal fails)
- External 4MHz–16MHz clock input

Crystal Selection

The MAXQ7667 requires a crystal with the following specifications:

Frequency: 1MHz–16MHz

 $C₁$ $OAD:$ $6pF$ (min)

Drive level: 5µW

Series resonance resistance: 30Ω (max)

Note: Quartz crystal vendors often specify series resonance resistance (R1). Series resonance resistance is the resistance observed when the resonator is in the series resonant condition. When a resonator is used in the parallel resonant mode with an external load capacitance, as is the case with the MAXQ7667 oscillator circuit, the effective resistance at the loaded frequency of oscillation is:

$R1 \times (1 + (CO/CLOAD))^2$

For typical shunt capacitance (CO) and load capacitance $(C_1 \cap A)$ values, the effective resistance potentially exceeds R1 by a factor of 2.

MAXQ is a registered trademark of Maxim Integrated Products, Inc.

Figure 8. Schedule-Timer Module Block Diagram

Figure 9. Type 2 Timer/Counter in 16-Bit Mode

MAXM

JTAG Interface

The joint test action group (JTAG) IEEE 1149.1 standard defines a unique method for in-circuit testing and programming. The MAXQ7667 conforms to this standard, implementing an external test access port (TAP) and internal TAP controller for communication with a JTAG bus master, such as an automatic test equipment (ATE) system. The MAXQ7667 JTAG interface does not allow boundary scan. For detailed information on the TAP and TAP controller, refer to IEEE Std 1149.1 "IEEE Standard Test Access Port and Boundary-Scan Architecture" on the IEEE website at www.standards.ieee.org.

The TAP controller communicates synchronously with the host system (bus master) through four digital I/Os: test mode select (TMS), test clock (TCK), test data input (TDI), and test data output (TDO). The internal TAP module consists of shift registers and a TAP controller (Figure 10). The shift registers serve as transmit and receive data buffers for a debugger. Maintain the maximum TCK clock frequency to below 1/8 the system clock frequency for proper operation.

Figure 10. JTAG Interface Block Diagram

MAXQ7667

MAXQ7667

The following four digital I/Os form the TAP interface:

- TDO—Serial output signal for test instruction and data. Data transitions on the falling edge of TCK. TDO idles high when inactive. TDO serially transfers internal data to the external host. Data transfers lease significant bit first.
- TDI—Serial input signal for test instruction and data. Transition data on the rising edge of TCK. TDO pulls high when unconnected. TDI serially transfers data from the external host to the internal TAP module shift registers. Data transfers least significant bit first.
- TCK—Serial clock for the test logic. When TCK stops at 0, storage elements in the test logic must retain their data indefinitely. Force TCK high when inactive.
- TMS—Test mode selection. The rising edge of TCK samples the test signals at TMS. The TAP controller decodes the test signals at TMS to control the test operation. Force TMS high when inactive.

UART/LIN Interface

The MAXQ7667 includes a UART/LIN transceiver combination that supports communication speeds up 2MBd. The LIN standard for example limits communication speed to 20kBd or less. Connect a LIN transceiver or other UART connections such as RS-232 and RS-485 directly to the MAXQ7667's 2-wire interface: URX and UTX. The MAXQ7667 operates as a LIN slave or LIN master device. The UART provides the programmable baud-rate generators to communicate effectively to or from the LIN transceiver. The device holds up to 8 bytes of data in each of the transmit and receive FIFOs. The following characteristics apply to the MAXQ7667 UART/LIN interface:

- Full-duplex operation for asynchronous data transfers up to 500kBd (system clock/32)
- Half-duplex operation for synchronous data transfers up to 2MBd (system clock/8)
- 8-deep receive and transmit FIFO with programmable interrupt for receive and transmit
- Independent baud-rate generator
- Programmable 9th data bit (commonly used for parity or address/data selection)—UART mode only
- Hardware support for LIN including break detection, autobaud, address identity filtering, checksum calculation, and block length checking

• Supports common RS-232 and LIN baud rates: 1000, 1200, 2400, 4800, 9600, 19,200, 20,000, 38,400, 57,600, and 115,200 with system clock = 16MHz.

SPI Interface

The MAXQ7667 supports 4-wire SPI interface communication with 8-bit or 16-bit data streams operating in either master mode or slave mode. The SPI interface allows synchronous half-duplex or full-duplex serial data transfers to a wide variety of external serial devices using MISO, MOSI, SS, and SCLK signals. Collision detection is provided when two or more masters attempt a data transfer at the same time. See Section 9 of the MAXQ7667 User's Guide.

General-Purpose Digital I/O Ports

Two 8-bit digital I/O ports (P0._ and P1._), with dedicated one or more alternative functions, are available as general-purpose I/Os (GPIOs) under the control of the integrated MAXQ20. Set each I/O within each port individually as an input or output. The GPIOs incorporate a Schmitt trigger receiver and a full CMOS output driver (Figure 13). Each GPIO configures as an input with pullup to DVDDIO at power-up. When programmed as an input, each I/O is configurable for high-impedance, weak pullup to DVDDIO or pulldown to DGND. When programmed as an output, writing to the port output register (PO) controls the output logic state. The outputs source or sink at least 1.6mA. Configure the drive strength for each I/O within each port to high or low using the pad drive strength register for optimum EMI performance. All the I/O ports have interrupt capability that wake up the device while in stop mode and have protection circuitry to DVDDIO and DGND.

Supply-Voltage Regulators

The MAXQ7667 requires three different power-supply voltages. DVDDIO, nominally +5V, allows interfacing to standard 5V logic on all the digital I/Os including the LIN/UART, JTAG, and SPI ports. DVDD, nominally +2.5V, powers all the high-speed digital circuits. AVDD, nominally 3.3V, powers the analog circuits.

External power supplies or internal voltage regulators provide each of the supply voltages. The internal voltage regulators provide 3.3V and 2.5V supplies from the 5V DVDDIO input. Obtain the 5V supply from a higher external voltage supply by using a few external components. The MAXQ7667 includes an internal error amplifier used to regulate the voltage on DVDDIO by driving the gate or base of an external pass transistor. Refer to the MAXQ7667 User's Guide for more details on the external components needed for 5V regulation.

Figure 11. SPI Timing Diagram in Master Mode

Figure 12. SPI Timing Diagram in Slave Mode

MAXM

MAXQ7667

MAXQ7667

Figure 13. Port 0 Digital I/O Basic Circuitry. Port 1 Circuitry is the Same as Port 2.

Connect bypass capacitors at each power-supply input as close as possible to the device. Use a bypass capacitor less than 0.47µF on DVDDIO. For most applications, 0.1µF bypass capacitors are adequate.

Supply Brownout Monitor

Power supplies DVDD, AVDD, and DVDDIO each include a brownout monitor/supervisor that alerts the µC when their corresponding supply voltages drop below the interrupt threshold. Activate each brownout monitor independently using the corresponding brownout enable bits: VDBE, VIBE, and VABE.

Reset

In reset mode, no instruction execution occurs and all inputs/outputs return to their default states. Code execution resumes at address 8000h (in the utility ROM) once the reset condition is removed.

Four different sources reset the MAXQ7667: POR, watchdog timer reset, external reset, and internal system reset.

During normal operation, force RESET low for at least four system clock cycles for an external reset. Set the ROD bit in the SC register, while the SPE bit in the ICDF register is set, for an internal system reset. See Section 16 of the MAXQ7667 User's Guide.

Power-On Reset (POR)

The MAXQ7667 includes a DVDD voltage supervisor to control the µC POR. On power-up, internal circuitry pulls RESET low and resets all the internal registers. RESET is held low for the duration of the power-on delay after VDVDD rises above the DVDD reset threshold. The internal RC oscillator starts up and software execution begins at the reset vector location 8000h immediately after the device exits POR while RESET is

not externally forced low. An internal POR flag indicates the source of a reset. Ramp up the DVDD supply at a minimum rate of 60mV/ms to keep the device in POR until DVDD fully settles.

Watchdog Timer

The primary function of the watchdog timer is to watch for stalled or stuck software. The watchdog timer performs a controlled system restart when the µP fails to write to the watchdog timer register before a selectable timeout interval expires. The internal 13.5MHz RC oscillator drives the MAXQ7667's watchdog timer.

Figure 14 shows the watchdog timer functions as the source of both the watchdog interrupt and watchdog reset. The watchdog interrupt timeout period is programmable to 212, 215, 218, or 221 cycles of the RC oscillator resulting in a nominal range of 273µs to 139.8ms. The watchdog reset timeout period is a fixed 512 RC clock cycles (34µs). When enabled, the watchdog generates an interrupt upon expiration; then, if not reset within 512 RC clock cycles, the watchdog asserts RESET low for eight RC clock cycles.

Hardware Multiplier/Accumulator

A hardware multiplier supports high-speed multiplications. The multiplier completes a 16-bit x 16-bit multiplication in a single clock cycle and contains a 48-bit accumulator. The multiplier is a peripheral that performs seven different multiplication operations:

- Unsigned 16-bit multiplication
- Unsigned 16-bit multiplication and accumulation
- Unsigned 16-bit multiplication and subtraction

Figure 14. Watchdog Functional Diagram

- Signed 16-bit multiplication
- Signed 16-bit multiplication and negation
- Signed 16-bit multiplication and accumulation
- Signed 16-bit multiplication and subtraction

MAXQ Core Architecture

The MAXQ20 µC is an accumulator-based Harvard memory architecture. Fetch and execution operations complete in one clock cycle without pipelining because the instruction contains both the op code and data. The µC streamlines 16 million instructions per second (MIPS). Integrated 16-level hardware stack enables fast subroutine calling and task switching. Manipulate data quickly and efficiently with three internal data pointers. Multiple data pointers allow more than one function to access data memory without having to save and restore data pointers each time. The data pointers automatically increment or decrement following an operation, eliminating the need for software intervention.

Instruction Set

The instruction set consists of a total of 33 fixed-length 16-bit instructions that operate on registers and memory locations. The highly orthogonal instruction set allows arithmetic and logical operations to use any register along with the accumulator. System registers control functionality common to all MAXQ µCs, while peripheral registers control peripherals and functions specific to the MAXQ7667. All registers are subdivided into register modules.

The architecture is transport-triggered. Writes or reads from certain register locations potentially have side effects. These side effects form the basis for the higher level op codes defined by the assembler, such as ADDC, OR, JUMP, etc. The op codes are implemented as MOVE instructions between system registers. The assembler handles all the instruction encoding.

Memory Organization

In addition to the internal register space, the device incorporates several memory areas:

- 16Kwords of flash memory for program storage
- 2Kword of SRAM for storage of temporary variables
- 4Kwords utility ROM
- 16-level, 16-bit-wide hardware stack for storage of program return addresses and general-purpose use

Use the internal memory-management unit (MMU) to map data memory space into a predefined program memory segment for code execution from data memory. Use the MMU to map program memory space as data space for access to constant data stored in program

Data Memory

memory. Access physical memory segments (other than the stack and register memories) as either program memory or data memory, but not both at once.

By default, the memory is arranged in a Harvard architecture, with separate address spaces for program and data memory. The configuration of program and data space depends on the current execution location.

- When executing code from flash memory, access the SRAM and utility ROM in data space.
- When executing code from SRAM, access the flash memory and utility ROM in data space.
- When executing code from the utility ROM, access the flash memory and SRAM in data space.

Utility ROM (see Section 18 of the MAXQ7667 User's Guide)

The utility ROM is a 4K x 16 block of internal ROM memory that defaults to a starting address of 8000h. The utility ROM consists of subroutines called from application software. The subroutines include:

- In-system programming (bootloader) over the JTAG or UART interface
- In-circuit debug routines
- Test routines (internal memory tests, memory loader, etc.)
- User-callable routines for in-application flash programming and code space table lookup

Following any reset, execution begins in the utility ROM. The ROM software determines whether the program execution immediately jumps to the start of the userapplication code (located at address 0000h) or to one of the special routines mentioned above. Call the routines within the utility ROM using the application software. Refer to the MAXQ7667 User's Guide for more information on the utility ROM contents.

Password protect in-system programming, in-application programming, and in-circuit debugging functions using a password-lock (PWL) bit. The PWL bit is implemented in the SC register. When the PWL bit is set to one (POR default), the password is required to access the utility ROM, including in-circuit debug and in-system programming routines that allow reading or writing of internal memory. When the PWL bit is cleared to zero, these utilities are fully accessible without the password. The password is automatically set to all ones following a mass erase.

The 2K x 16 internal data SRAM maps into either program or data space. The contents of the SRAM are maintained during stop mode and across non-POR resets, as long as DVDD remains within the operating voltage range.

A data memory cycle requires only one system clock period to support fast internal execution. This allows a complete read or write operation on SRAM in one clock cycle. The MMU handles data memory mapping and access control. Read or write to the data memory with word or byte-wide commands.

Stack Memory

The MAXQ7667 provides a 16 x 16 hardware stack to support subroutine calls and system interrupts. A 16-bit wide internal hardware stack provides storage for program return addresses and general-purpose use. The stack is used automatically by the processor when the CALL, RET, and RETI instructions are executed and interrupts serviced.

Register Set

Sets of registers control most functions. These registers provide a working space for memory operations as well as configuring and addressing peripheral registers on the device. Registers are divided into two major types; system registers and peripheral registers. The register set common to most MAXQ-based devices, also known as the system registers, includes the ALU, accumulator registers, data pointers, interrupt vectors and control, and stack pointer. The peripheral registers define additional functionality. Tables 1 and 3 show the MAXQ7667 register set.

Programming

Two different methods program the flash memory: insystem programming and in-application programming. Both methods afford great flexibility in system design as well as reduce the life-cycle cost of the embedded system. The MAXQ7667 password protects these features to prevent unauthorized access to code memory.

In-System Programming

An internal bootstrap loader reloads the device over a simple JTAG or UART interface allowing cost savings in system software upgrade. During power-up, the MAXQ7667 first checks for activity on the JTAG port. If no activity is present, the device checks if a passwordprotected program is present. If the password is set,

the application code executes. The application codes initiate reprogramming. If the password is not set, the MAXQ7667 monitors the UART for an autobaud character (0x0D). If this character is received, the device sets its serial baud rate and initiates a boot loader procedure. If 0x0D is not received after five seconds, the device begins execution of the application code.

The following bootloader functions are supported:

- Load
- Dump
- CRC
- Verify
- Erase

In-Application Programming

The in-application programming feature allows the μ C to modify its own flash program memory while simultaneously executing its application software. This allows on the fly software updates in mission-critical applications that cannot afford downtime. Erase and program the flash memory using the flash programming functions in the utility ROM. Refer to Section 18 of the MAXQ7667 User's Guide for a detailed description of the utility ROM functions.

Stop Mode

Power consumption reaches its minimum in stop mode $(STOP = 1)$. In this mode, the external oscillator, internal RC oscillator, system clock, and all processing halts. Trigger an enabled external interrupt input or directly apply an external reset on RESET to exit stop mode. Upon exiting stop mode, the µC either waits for the external high-frequency crystal to complete its warmup period or starts execution immediately from its internal RC oscillator while the crystal warms up.

Interrupts

Multiple interrupt sources quickly respond to internal and external events. The MAXQ architecture uses a single interrupt vector (IV) and single interrupt-service routine (ISR) design. Enable interrupts globally, individually, or by module. When an interrupt condition occurs, its individual flag is set even if the interrupt source is disabled at the local, module, or global level. Clear interrupt flags within the interrupt routine to avoid repeated false interrupts from the same source. Provide an adequate delay between the write to the flag and the RETI instruction using application software to allow time for the interrupt hardware to remove the internal interrupt condition. Asynchronous interrupt flags require a one-instruction delay and synchronous interrupt flags require a two-instruction delay.

When an enabled interrupt is detected, software jumps to a user-programmable interrupt vector location. The IV register defaults to 0000h on reset or power-up. Once software control transfers to the ISR, use the interrupt identification register (IIR) to determine if the source of the interrupt is a system register or peripheral register. The specified module identifies the specific interrupt source. The following interrupt sources are available:

- Watchdog interrupt
- External interrupts 0–7 on port 0 and port 1
- Timer 0 low compare, low overflow, capture/compare, and overflow interrupts
- Timer 1 low compare, low overflow, capture/compare, and overflow interrupts
- Timer 2 low compare, low overflow, and overflow interrupts
- Schedule timer alarm interrupt
- SPI data transfer complete, mode fault, write collision and receive overrun interrupts
- UART transmit, receive interrupts
- LIN mode master or slave interrupt
- SAR ADC data ready interrupt
- Echo envelope LPF output, FIFO full, and comparator interrupts
- Digital and I/O voltage brownout interrupts
- High-frequency oscillator failure interrupt

Table 1. System Register Map

REGISTER MODULE NAME (BASE SPECIFIER)
INDEX AP (8b) A (9b) PFX (Bb) IP (Cb) SP (D) **INDEX AP (8h) A (9h) PFX (Bh) IP (Ch) SP (Dh) DPC (Eh) DP (Fh)** 0h | AP | **A[0] | PFX[0] | IP |** — | — | — 1h | APC | **A[1] | PFX[1]** | $-$ | SP | $-$ | $-$ 2h | — | **A[2] | PFX[2] |** — | IV | — | — 3h — **A[3] PFX[3]** — — OFFS **DP[0]** 4h PSF **A[4] PFX[4]** — — **DPC** — 5h IC **A[5] PFX[5]** — — **GR** — 6h IMR **A[6] PFX[6]** — **LC[0]** GRL — 7h — **A[7] PFX[7]** — **LC[1] BP DP[1]** 8h | SC | **A[8]** | — | — | *GRS* **| —** 9h — **A[9]** — — — GRH — Ah — **A[10]** — — — *GRXL* — Bh IIR **A[11]** — — — *FP* — Ch | — | **A[12]** | — | — | — | — | — Dh — **A[13]** — — — — — Eh | CKCN | **A[14]** | — | — | — | — | — Fh | WDCN | **A[15]** | — | — | — | — | —

Note: Registers in italics are read-only. Registers in bold are 16-bit wide.

Table 2. System Register Bit and Reset Values **Table 2. System Register Bit and Reset Values**

MXXVIVI

16-Bit, RISC, Microcontroller-Based, Ultrasonic Distance-Measuring System

MAXQ7667 MAXQ7667

MAXQ7667 **MAXQ7667**

16-Bit, RISC, Microcontroller-Based,

Ultrasonic Distance-Measuring System

Guide for more information.

Table 3. Peripheral Register Map

MAXQ7667 **MAXQ7667**

Table 4. Peripheral Register Bit Functions and Reset Values

16-Bit, RISC, Microcontroller-Based,

Ultrasonic Distance-Measuring System

MAXIM

16-Bit, RISC, Microcontroller-Based,

Ultrasonic Distance-Measuring System

Table 4. Peripheral Register Bit Functions and Reset Values (continued) **Table 4. Peripheral Register Bit Functions and Reset Values (continued)**

MXXVIVI

MAXG7667 MAXQ7667

__ 35

MAXQ7667 **MAXQ7667**

16-Bit, RISC, Microcontroller-Based, Ultrasonic Distance-Measuring System

Table 4. Peripheral Register Bit Functions and Reset Values (continued) **Table 4. Peripheral Register Bit Functions and Reset Values (continued)**

16-Bit, RISC, Microcontroller-Based, Ultrasonic Distance-Measuring System

MAXQ7667 **MAXQ7667**

8 Table 4, Peripheral Register B1F Emictions and Reset Values (continued)
 8 Table 4, Peripheral Register BF Emicions and Reset Values (continued)

From the Law and Law

MAXM

16-Bit, RISC, Microcontroller-Based, Ultrasonic Distance-Measuring System

Applications Information

Development and Technical Support

A variety of highly versatile, affordably priced development tools for this μ C are available from Maxim and third-party suppliers, including:

- Compilers
- Evaluation kit
- Integrated development environments (IDEs)
- JTAG-to-serial converters for programming and debugging

A partial list of development tool vendors can be found at **www.maxim-ic.com/MAXQ_tools**.

Technical support is available at **https://support.maximic.com/micro**.

Additional Documentation

Designers must have the following documents to fully use all the features of this device. This data sheet contains pin descriptions, feature overviews, and electrical specifications. Errata sheets contain deviations from published specifications. The user's guides offer detailed information about device features and operation. The following documents can be downloaded from **www.maxim-ic.com/microcontrollers**.

- This MAXQ7667 data sheet, which contains electrical/timing specifications and pin descriptions.
- The MAXQ7667 revision-specific errata sheet (**www.maxim-ic.com/errata**).
- The MAXQ7667 Family User's Guide, which contains detailed information on core features and operation, including programming.

Chip Information

PROCESS: CMOS

Package Information

For the latest package outline information and land patterns, go to **www.maxim-ic.com/packages**.

MAXIM __ 39

Pin Configuration MAXQ7667 MAXQ766